Revision: 1.0
Date: 7-Feb-05

Statement of Materials, Construction

LEAD-FREE -- 8L-PDIP -- TABLE OF MATERIAL DECLARATION								
No.	Component Name	Material Name	Component Weight (grams)	Materials Analysis (Element / Compound)	CAS Number	Material Mass (Gram)	Material Weight % (of Total Pkg)	Material Weight % (of Component)
1	Leadframe	Copper Alloy	0.15453	Cu	7440-50-8	0.15022	30.06329	97.213
				Fe	7439-89-6	0.00363	0.72674	2.35
				Pb	7439-92-1	0.00005	0.00928	0.03
				P	7723-14-0	0.00013	0.02551	0.0825
				Zn	7440-66-6	0.00019	0.03866	0.125
				Ag	7440-22-4	0.00031	0.06185	0.2
2	Die	Silicon Chip	0.00250	Si	7440-21-3	0.00249	0.49781	99.5
3	Die attach material	Conductive Epoxy	0.00090	Epoxy resin (5-25)	Proprietary	0.00014	0.02702	15
				Silver (70-85)	7440-21-3	0.00072	0.14319	79.5
				Aromatic Amine (1-10)	Proprietary	0.00005	0.00991	5.5
4	Wire	Gold	0.00026	Au	7440-57-5	0.00026	0.05203	99.99
5	Lead Finish	Tin	0.0131	Sn	7440-31-5	0.01310	2.62163	100
6	Encapsulation	Epoxy Resin	0.3284	Fused Silica	7631-86-9	0.22988	46.00452	70
				Epoxy resin	29690-82-2	0.05583	11.17253	17
				Phenol Resin	9003-35-4	0.02529	5.06050	7.7
				Antimony trioxide	1309-64-4	0.00985	1.97162	3
				Brominated Epoxy Resin	40039-93-8	0.00657	1.31441	2
				Carbon Black	1333-86-4	0.00099	0.19716	0.3
Total Package weight			0.49969					

Note: Composition derived from MSDS and material C of C from Vendors;
Component Weight based on assembly of generic parts.

Conclusion:

The analysis table above shows that this package meets the following RoHS requirements for EACH PACKAGE COMPONENT (mold compound, lead frame, etc.)

	Maximum Allowable Limit (ppm)	Maximum Allowable Limit (wt %)
Lead*	1000 ppm	0.10%
Mercury	1000 ppm	0.10%
Cadmium	100 ppm	0.01%
Hexavalent Chromium	1000 ppm	0.10%
Polybrominated Biphenyls (PBB)	1000 ppm	0.10%
Polybrominated Biphenylethers (PBDE)	1000 ppm	0.10%

* Lead is allowed up to 4% as an alloying agent in copper-based alloys